93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

4K Microwire Compatible Serial EEPROM

Device Selection Table

Part Number	Vcc Range	ORG Pin	Word Size	Temp Ranges	Packages
93AA66A	1.8-5.5	No	8-bit	I	P, SN, ST, MS, OT
93AA66B	1.8-5-5	No	16-bit	I	P, SN, ST, MS, OT
93LC66A	2.5-5.5	No	8-bit	I, E	P, SN, ST, MS, OT
93LC66B	2.5-5.5	No	16-bit	I, E	P, SN, ST, MS, OT
93C66A	4.5-5.5	No	8-bit	I, E	P, SN, ST, MS, OT
93C66B	4.5-5.5	No	16-bit	I, E	P, SN, ST, MS, OT
93AA66C	1.8-5.5	Yes	8 or 16-bit	I	P, SN, ST, MS
93LC66C	2.5-5.5	Yes	8 or 16-bit	I, E	P, SN, ST, MS
93C66C	4.5-5.5	Yes	8 or 16-bit	I, E	P, SN, ST, MS

Features

- Low-power CMOS technology
- ORG pin to select word size for ‘66C version
- 512 x 8-bit organization ‘A’ ver. devices (no ORG)
- 256 x 16-bit organization ‘B’ ver. devices (no ORG)
- Self-timed ERASE/WRITE cycles (including auto-erase)
- Automatic ERAL before WRAL
- Power on/off data protection circuitry
- Industry standard 3-wire serial I/O
- Device Status signal (READY/$\overline{\text{BUSY}}$)
- Sequential READ function
- 1,000,000 E/W cycles
- Data retention > 200 years
- Temperature ranges supported:
  - Industrial (I) -40°C to +85°C
  - Automotive (E) -40°C to +125°C

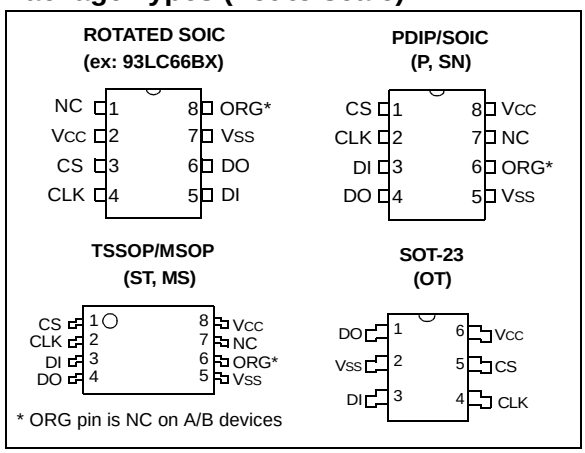
Pin Function Table

Name	Function
CS	Chip Select
CLK	Serial Data Clock
DI	Serial Data Input
DO	Serial Data Output
VSS	Ground
NC	No internal connection
ORG	Memory Configuration
VCC	Power Supply

Description

The Microchip Technology Inc. 93XX66A/B/C devices are 4K bit low voltage serial Electrically Erasable PROMs (EEPROM). Word-selectable devices such as the 93AA66C, 93LC66C or 93C66C are dependent upon external logic levels driving the ORG pin to set word size. For dedicated 8-bit communication, the 93AA66A, 93LC66A or 93C66A devices are available, while the 93AA66B, 93LC66B and 93C66B devices provide dedicated 16-bit communication. Advanced CMOS technology makes these devices ideal for low power, non-volatile memory applications. The entire 93XX Series is available in standard packages including 8-lead PDIP and SOIC, and advanced packaging including 8-lead MSOP, 6-lead SOT-23, and 8-lead TSSOP. Pb-free (Pure Matte Sn) finish is also available.

Package Types (not to scale)



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings(†)

VCC.....7.0V

All inputs and outputs w.r.t. VSS ..... -0.6V to VCC +1.0V

Storage temperature .....-65°C to +150°C

Ambient temperature with power applied.....-40°C to +125°C

ESD protection on all pins .....≥ 4 kV

† **NOTICE:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: DC CHARACTERISTICS

All parameters apply over the specified ranges unless otherwise noted.			VCC = range by device (see Table on Page 1) Industrial (I): TA = -40°C to +85°C Automotive (E): TA = -40°C to +125°C				
Param. No.	**Symbol**	**Parameter**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
D1	VIH1 VIH2	High-level input voltage	2.0 0.7 VCC	— —	VCC +1 VCC +1	V V	VCC ≥ 2.7V VCC < 2.7V
D2	VIL1 VIL2	Low-level input voltage	-0.3 -0.3	— —	0.8 0.2 VCC	V V	VCC ≥ 2.7V VCC < 2.7V
D3	VOL1 VOL2	Low-level output voltage	— —	— —	0.4 0.2	V V	IOL = 2.1 mA, VCC = 4.5V IOL = 100 µA, VCC = 2.5V
D4	VOH1 VOH2	High-level output voltage	2.4 VCC - 0.2	— —	— —	V V	IOH = -400 µA, VCC = 4.5V IOH = -100 µA, VCC = 2.5V
D5	ILI	Input leakage current	—	—	±1	µA	VIN = VSS to VCC
D6	ILO	Output leakage current	—	—	±1	µA	VOUT = VSS to VCC
D7	CIN, COUT	Pin capacitance (all inputs/ outputs)	—	—	7	pF	VIN/VOUT = 0V **(Note 1)** TA = 25°C, FCLK = 1 MHz
D8	ICC write	Write current	— —	— 500	2 —	mA µA	FCLK = 3 MHz, Vcc = 5.5V FCLK = 2 MHz, Vcc = 2.5V
D9	ICC read	Read current	— — —	— — 100	1 500 —	mA µA µA	FCLK = 3 MHz, VCC = 5.5V FCLK = 2 MHz, VCC = 3.0V FCLK = 2 MHz, VCC = 2.5V
D10	ICCS	Standby current	— —	— —	1 5	µA µA	I – Temp E – Temp CLK = Cs = 0V ORG = DI = VSS or VCC **(Note 2) (Note 3)**
D11	VPOR	VCC voltage detect 93AA66A/B/C, 93LC66A/B/C 93C66A/B/C	— —	1.5V 3.8V	— —	V V	**(Note 1)**

Note 1: This parameter is periodically sampled and not 100% tested.

2: ORG pin not available on ‘A’ or ‘B’ versions.

3: READY/$\overline{\text{BUSY}}$ status must be cleared from DO, see **Section 3.4 "Data Out (DO)"**.

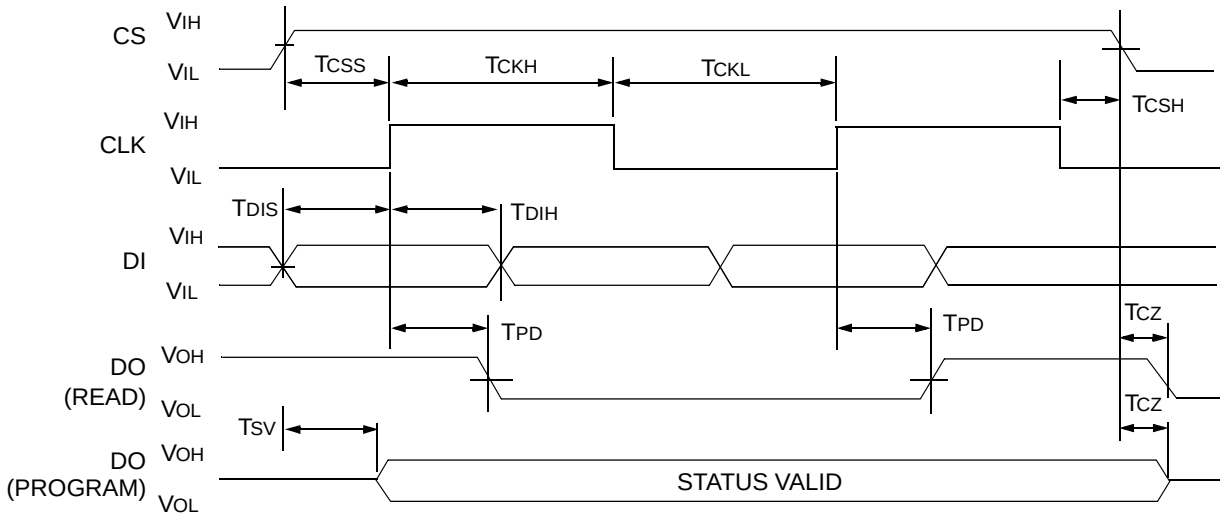
TABLE 1-2: AC CHARACTERISTICS

All parameters apply over the specified ranges unless otherwise noted.			VCC = range by device (see Table on Page 1) Industrial (I): TA = -40°C to +85°C Automotive (E): TA = -40°C to +125°C			
Param. No.	**Symbol**	**Parameter**	**Min**	**Max**	**Units**	**Conditions**
A1	FCLK	Clock frequency	— — —	3 2 1	MHz MHz MHz	4.5V ≤ VCC < 5.5V, 93XX66C only 2.5V ≤ VCC < 5.5V 1.8V ≤ VCC < 2.5V
A2	TCKH	Clock high time	200 250 450	— — —	ns ns ns	4.5V ≤ VCC < 5.5V, 93XX66C only 2.5V ≤ VCC < 5.5V 1.8V ≤ VCC < 2.5V
A3	TCKL	Clock low time	100 200 450	— — —	ns ns ns	4.5V ≤ VCC < 5.5V, 93XX66C only 2.5V ≤ VCC < 5.5V 1.8V ≤ VCC < 2.5V
A4	TCSS	Chip Select setup time	50 100 250	— — —	ns ns ns	4.5V ≤ VCC < 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
A5	TCSH	Chip Select hold time	0	—	ns	1.8V ≤ VCC < 5.5V
A6	TCSL	Chip Select low time	250	—	ns	1.8V ≤ VCC < 5.5V
A7	TDIS	Data input setup time	50 100 250	— — —	ns ns ns	4.5V ≤ VCC < 5.5V, 93XX66C only 2.5V ≤ VCC < 5.5V 1.8V ≤ VCC < 2.5V
A8	TDIH	Data input hold time	50 100 250	— — —	ns ns ns	4.5V ≤ VCC < 5.5V, 93XX66C only 2.5V ≤ VCC < 5.5V 1.8V ≤ VCC < 2.5V
A9	TPD	Data output delay time	—	200 250 400	ns ns ns	4.5V ≤ VCC < 5.5V, CL = 100 pF 2.5V ≤ VCC < 4.5V, CL = 100 pF 1.8V ≤ VCC < 2.5V, CL = 100 pF
A10	TCZ	Data output disable time	—	100 200	ns ns	4.5V ≤ VCC < 5.5V, **(Note 1)** 1.8V ≤ VCC < 4.5V, **(Note 1)**
A11	TSV	Status valid time	—	200 300 500	ns ns ns	4.5V ≤ VCC < 5.5V, CL = 100 pF 2.5V ≤ VCC < 4.5V, CL = 100 pF 1.8V ≤ VCC < 2.5V, CL = 100 pF
A12	TWC	Program cycle time	—	6	ms	Erase/Write mode (AA and LC versions)
A13	TWC		—	2	ms	Erase/Write mode (93C versions)
A14	TEC		—	6	ms	ERAL mode, 4.5V ≤ VCC ≤ 5.5V
A15	TWL		—	15	ms	WRAL mode, 4.5V ≤ VCC ≤ 5.5V
A16	—	Endurance	1M	—	cycles	25°C, VCC = 5.0V, **(Note 2)**

Note 1: This parameter is periodically sampled and not 100% tested.

2: This application is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which may be obtained from www.microchip.com.

FIGURE 1-1: SYNCHRONOUS DATA TIMING



Note: TSV is relative to CS.

TABLE 1-3: INSTRUCTION SET FOR X 16 ORGANIZATION (93XX66B OR 93XX66C WITH ORG = 1)

Instruction	SB	Opcode	Address								Data In	Data Out	Req. CLK Cycles
ERASE	1	11	A7	A6	A5	A4	A3	A2	A1	A0	—	(RDY/$\overline{\text{BSY}}$)	11
ERAL	1	00	1	0	X	X	X	X	X	X	—	(RDY/$\overline{\text{BSY}}$)	11
EWDS	1	00	0	0	X	X	X	X	X	X	—	HIGH-Z	11
EWEN	1	00	1	1	X	X	X	X	X	X	—	HIGH-Z	11
READ	1	10	A7	A6	A5	A4	A3	A2	A1	A0	—	D15 – D0	27
WRITE	1	01	A7	A6	A5	A4	A3	A2	A1	A0	D15 – D0	(RDY/$\overline{\text{BSY}}$)	27
WRAL	1	00	0	1	X	X	X	X	X	X	D15 – D0	(RDY/$\overline{\text{BSY}}$)	27

TABLE 1-4: INSTRUCTION SET FOR X 8 ORGANIZATION (93XX66A OR 93XX66C WITH ORG = 0)

Instruction	SB	Opcode	Address									Data In	Data Out	Req. CLK Cycles
ERASE	1	11	A8	A7	A6	A5	A4	A3	A2	A1	A0	—	(RDY/$\overline{\text{BSY}}$)	12
ERAL	1	00	1	0	X	X	X	X	X	X	X	—	(RDY/$\overline{\text{BSY}}$)	12
EWDS	1	00	0	0	X	X	X	X	X	X	X	—	HIGH-Z	12
EWEN	1	00	1	1	X	X	X	X	X	X	X	—	HIGH-Z	12
READ	1	10	A8	A7	A6	A5	A4	A3	A2	A1	A0	—	D7 – D0	20
WRITE	1	01	A8	A7	A6	A5	A4	A3	A2	A1	A0	D7 – D0	(RDY/$\overline{\text{BSY}}$)	20
WRAL	1	00	0	1	X	X	X	X	X	X	X	D7 – D0	(RDY/$\overline{\text{BSY}}$)	20

2.0 FUNCTIONAL DESCRIPTION

When the ORG* pin is connected to VCC, the (x16) organization is selected. When it is connected to ground, the (x8) organization is selected. Instructions, addresses and write data are clocked into the DI pin on the rising edge of the clock (CLK). The DO pin is normally held in a HIGH-Z state except when reading data from the device, or when checking the READY/BUSY status during a programming operation. The READY/BUSY status can be verified during an Erase/Write operation by polling the DO pin; DO low indicates that programming is still in progress, while DO high indicates the device is ready. DO will enter the HIGH-Z state on the falling edge of CS.

2.1 Start Condition

The Start bit is detected by the device if CS and DI are both high with respect to the positive edge of CLK for the first time.

Before a Start condition is detected, CS, CLK, and DI may change in any combination (except to that of a Start condition), without resulting in any device operation (READ, WRITE, ERASE, EWEN, EWDS, ERAL, or WRAL). As soon as CS is high, the device is no longer in Standby mode.

An instruction following a Start condition will only be executed if the required opcode, address and data bits for any particular instruction are clocked in.

2.2 Data In/Data Out (DI/DO)

It is possible to connect the Data In and Data Out pins together. However, with this configuration it is possible for a “bus conflict” to occur during the “dummy zero” that precedes the Read operation, if A0 is a logic high level. Under such a condition the voltage level seen at Data Out is undefined and will depend upon the relative impedances of Data Out and the signal source driving A0. The higher the current sourcing capability of A0, the higher the voltage at the Data Out pin. In order to limit this current, a resistor should be connected between DI and DO.

2.3 Data Protection

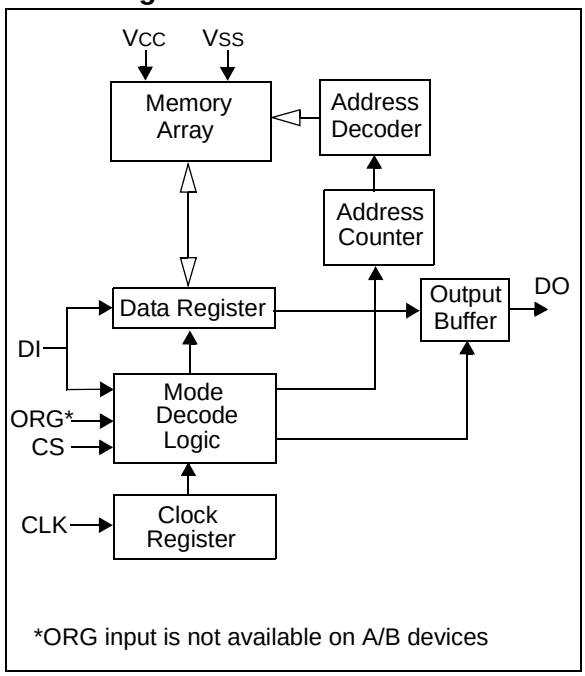
All modes of operation are inhibited when VCC is below a typical voltage of 1.5V for '93AA' and '93LC' devices or 3.8V for '93C' devices.

The EWEN and EWDS commands give additional protection against accidentally programming during normal operation.

Note: For added protection, an EWDS command should be performed after every write operation.

After power-up, the device is automatically in the EWDS mode. Therefore, an `EWEN` instruction must be performed before the initial `ERASE` or `WRITE` instruction can be executed.

Block Diagram



2.4 ERASE

The ERASE instruction forces all data bits of the specified address to the logical ‘1’ state. CS is brought low following the loading of the last address bit. This falling edge of the CS pin initiates the self-timed programming cycle, except on ‘93C’ devices where the rising edge of CLK before the last address bit initiates the write cycle.

The DO pin indicates the READY/$\overline{\text{BUSY}}$ status of the device if CS is brought high after a minimum of 250 ns low (T_{CSL}). DO at logical ‘0’ indicates that programming is still in progress. DO at logical ‘1’ indicates that the register at the specified address has been erased and the device is ready for another instruction.

Note: Issuing a Start bit and then taking CS low will clear the READY/$\overline{\text{BUSY}}$ status from DO.

FIGURE 2-1: ERASE TIMING FOR 93AA AND 93LC DEVICES

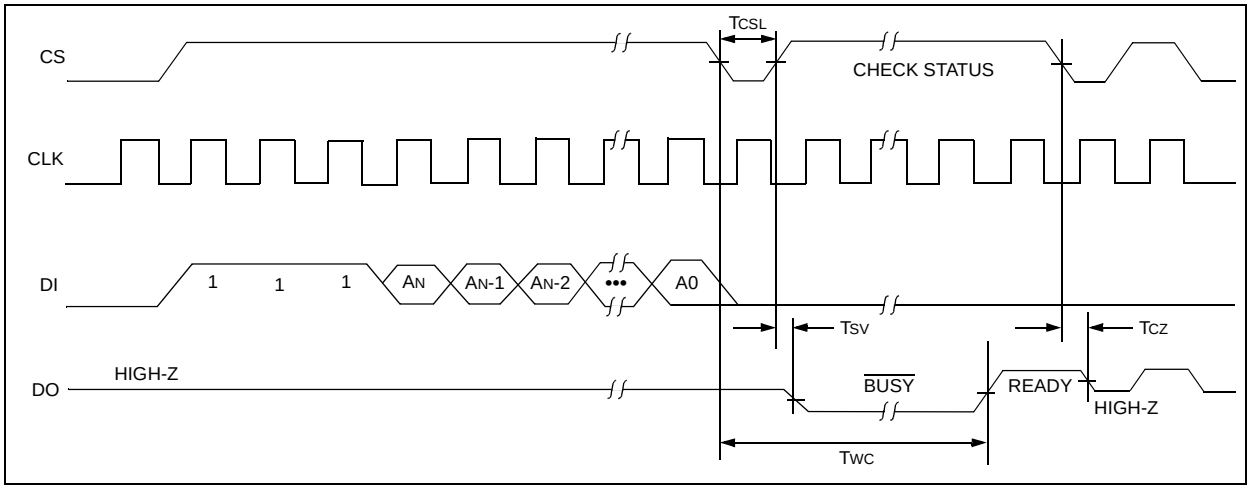
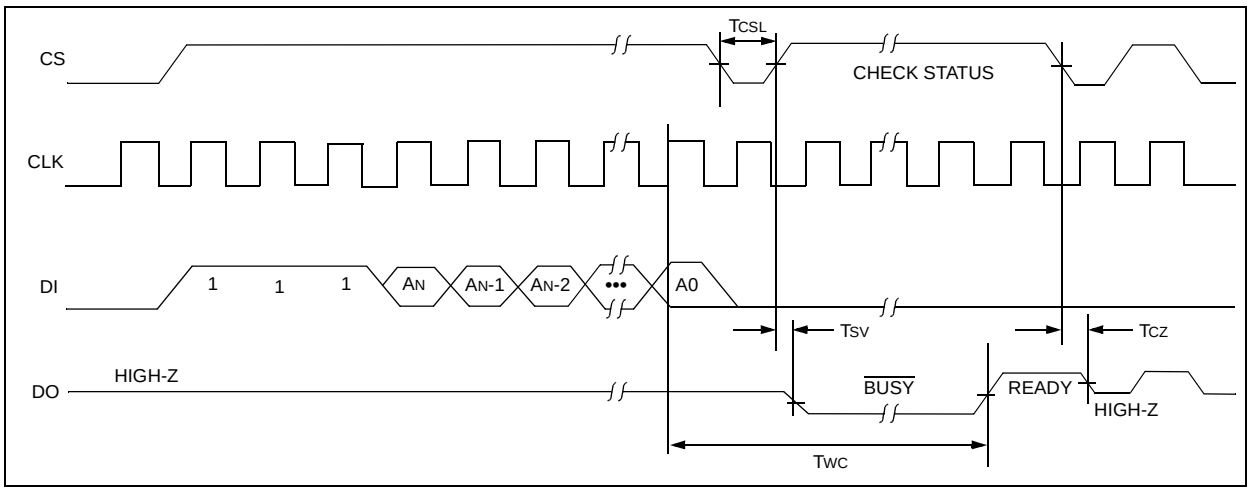


FIGURE 2-2: ERASE TIMING FOR 93C DEVICES



2.5 ERASE ALL (ERAL)

The Erase All (ERAL) instruction will erase the entire memory array to the logical '1' state. The ERAL cycle is identical to the ERASE cycle, except for the different opcode. The ERAL cycle is completely self-timed and commences at the falling edge of the CS, except on '93C' devices where the rising edge of CLK before the last data bit initiates the write cycle. Clocking of the CLK pin is not necessary after the device has entered the ERAL cycle.

The DO pin indicates the READY/$\overline{\text{BUSY}}$ status of the device, if CS is brought high after a minimum of 250 ns low (T_{CSL}).

Note: Issuing a Start bit and then taking CS low will clear the READY/$\overline{\text{BUSY}}$ status from DO.

V_{CC} must be ≥ 4.5V for proper operation of ERAL.

FIGURE 2-3: ERAL TIMING FOR 93AA AND 93LC DEVICES

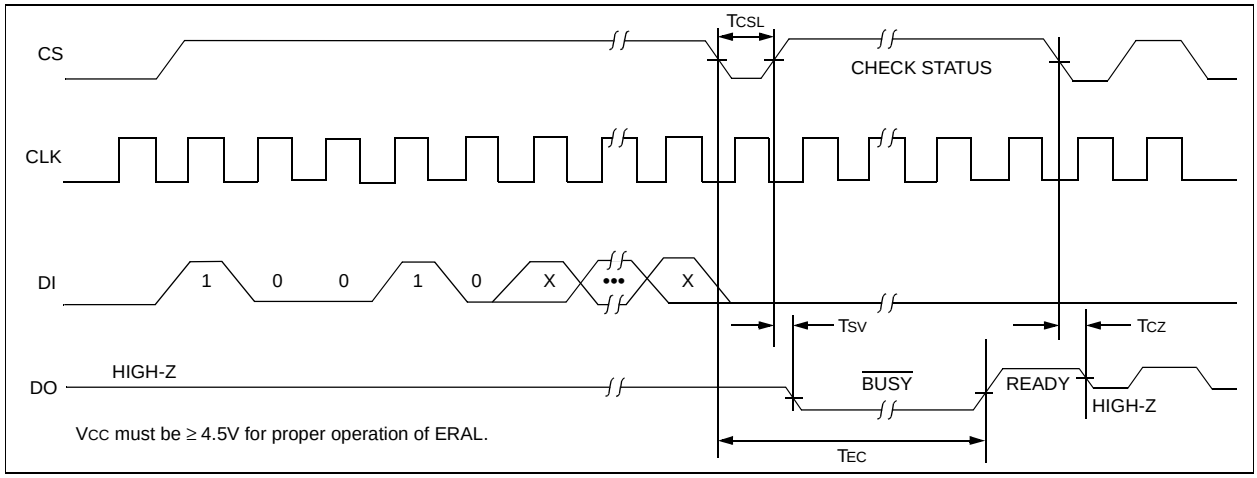
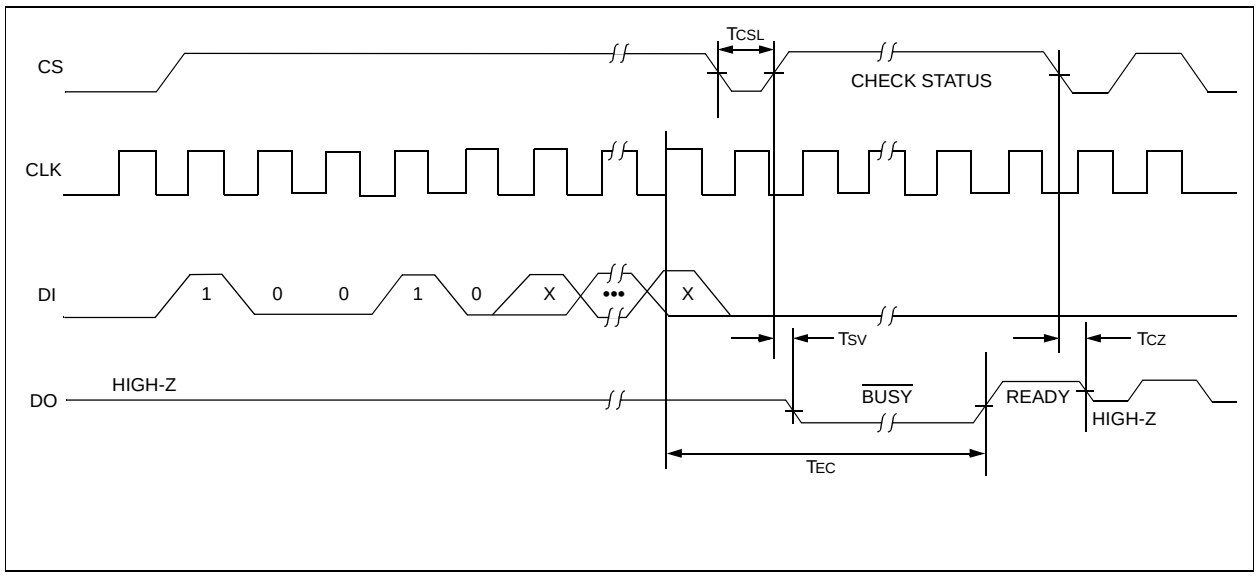


FIGURE 2-4: ERAL TIMING FOR 93C DEVICES



2.6 ERASE/WRITE DISABLE And ENABLE (EWDS/EWEN)

The 93XX66A/B/C powers up in the ERASE/WRITE Disable (EWDS) state. All Programming modes must be preceded by an ERASE/WRITE Enable (EWEN) instruction. Once the EWEN instruction is executed, programming remains enabled until an EWDS instruction is executed or Vcc is removed from the device.

To protect against accidental data disturbance, the EWDS instruction can be used to disable all ERASE/WRITE functions and should follow all programming operations. Execution of a READ instruction is independent of both the EWEN and EWDS instructions.

FIGURE 2-5: EWDS TIMING

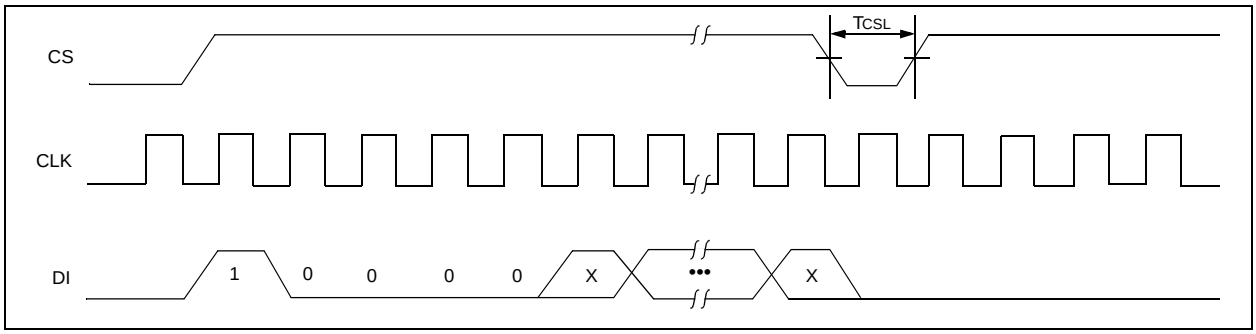
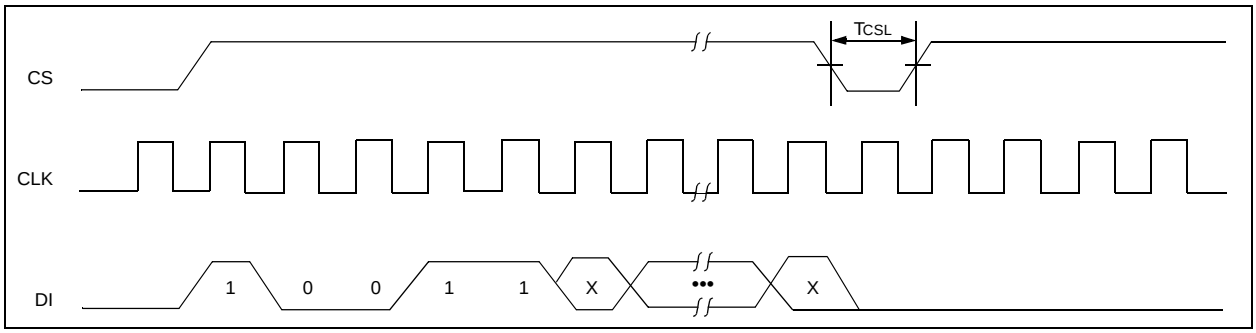


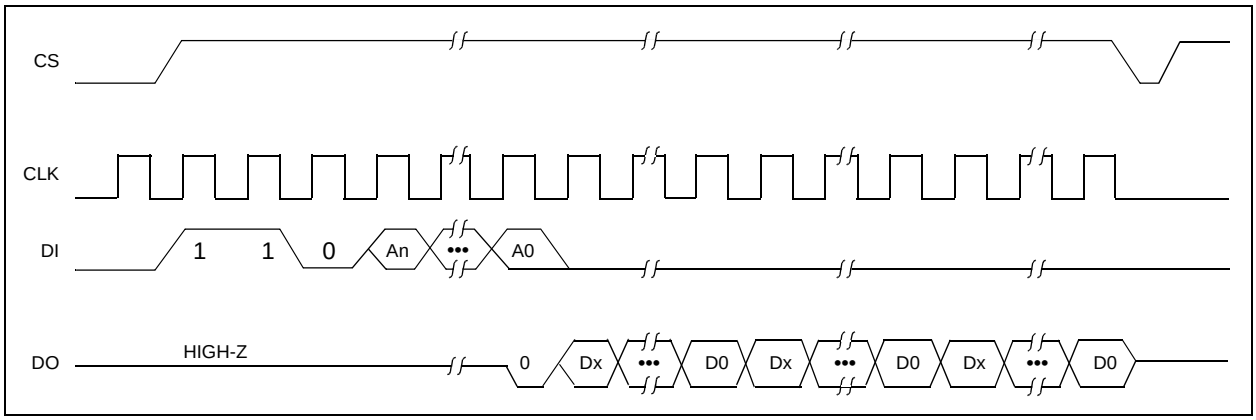
FIGURE 2-6: EWEN TIMING



2.7 READ

The READ instruction outputs the serial data of the addressed memory location on the DO pin. A dummy zero bit precedes the 8-bit (If ORG pin is low or A-Version devices) or 16-bit (If ORG pin is high or B-version devices) output string. The output data bits will toggle on the rising edge of the CLK and are stable after the specified time delay (TPD). Sequential read is possible when CS is held high. The memory data will automatically cycle to the next register and output sequentially.

FIGURE 2-7: READ TIMING



2.8 WRITE

The WRITE instruction is followed by 8 bits (If ORG is low or A-version devices) or 16 bits (If ORG pin is high or B-version devices) of data which are written into the specified address. For 93AA66A/B/C and 93LC66A/B/C devices, after the last data bit is clocked into DI, the falling edge of CS initiates the self-timed auto-erase and programming cycle. For 93C66A/B/C devices, the self-timed auto-erase and programming cycle is initiated by the rising edge of CLK on the last data bit.

The DO pin indicates the READY/$\overline{\text{BUSY}}$ status of the device, if CS is brought high after a minimum of 250 ns low (T_{CSL}). DO at logical '0' indicates that programming is still in progress. DO at logical '1' indicates that the register at the specified address has been written with the data specified and the device is ready for another instruction.

Note: Issuing a Start bit and then taking CS low will clear the READY/$\overline{\text{BUSY}}$ status from DO.

FIGURE 2-8: WRITE TIMING FOR 93AA AND 93LC DEVICES

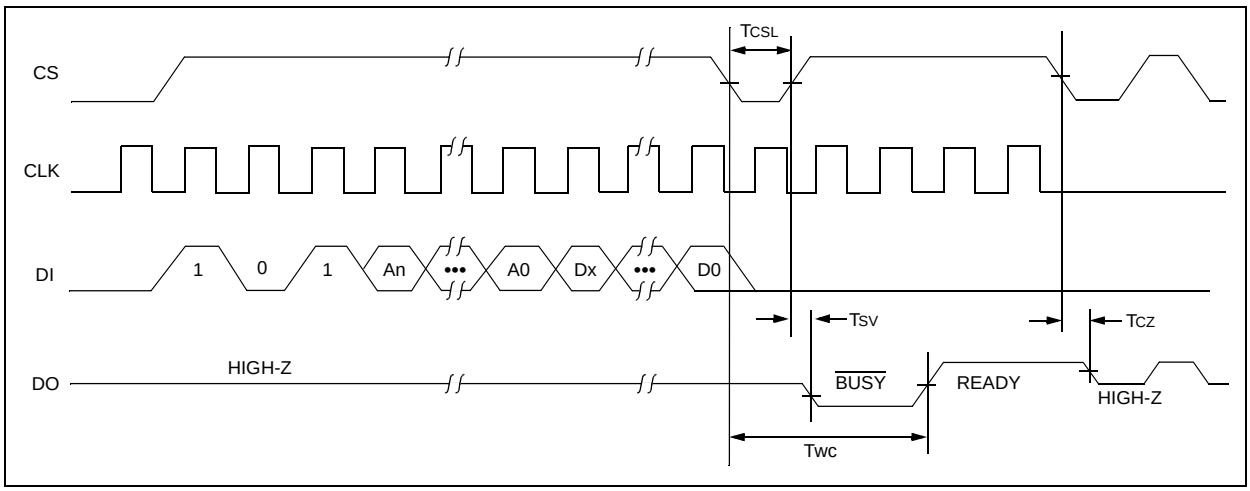
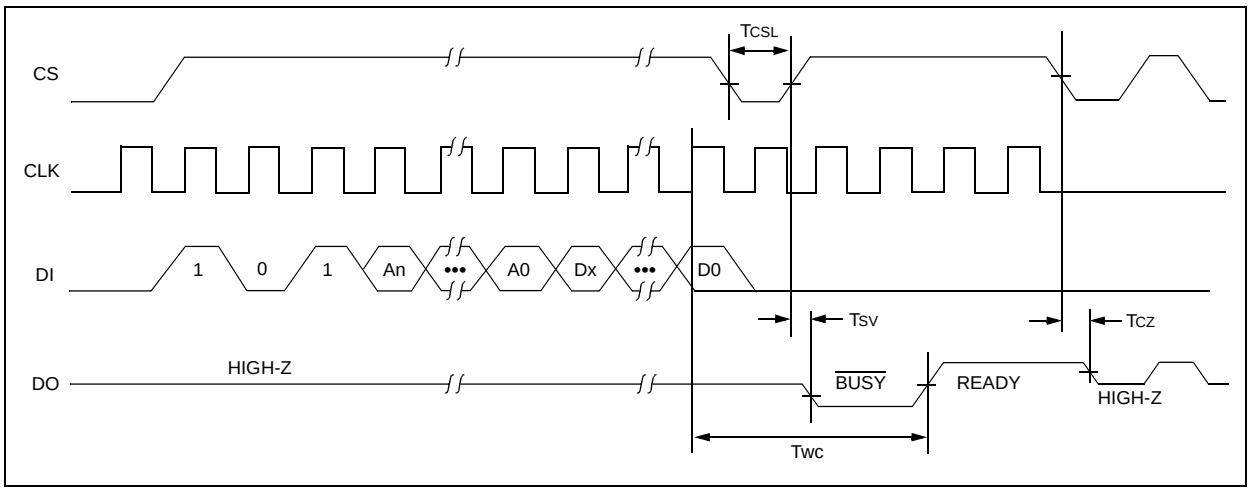


FIGURE 2-9: WRITE TIMING FOR 93C DEVICES



2.9 WRITE ALL (WRAL)

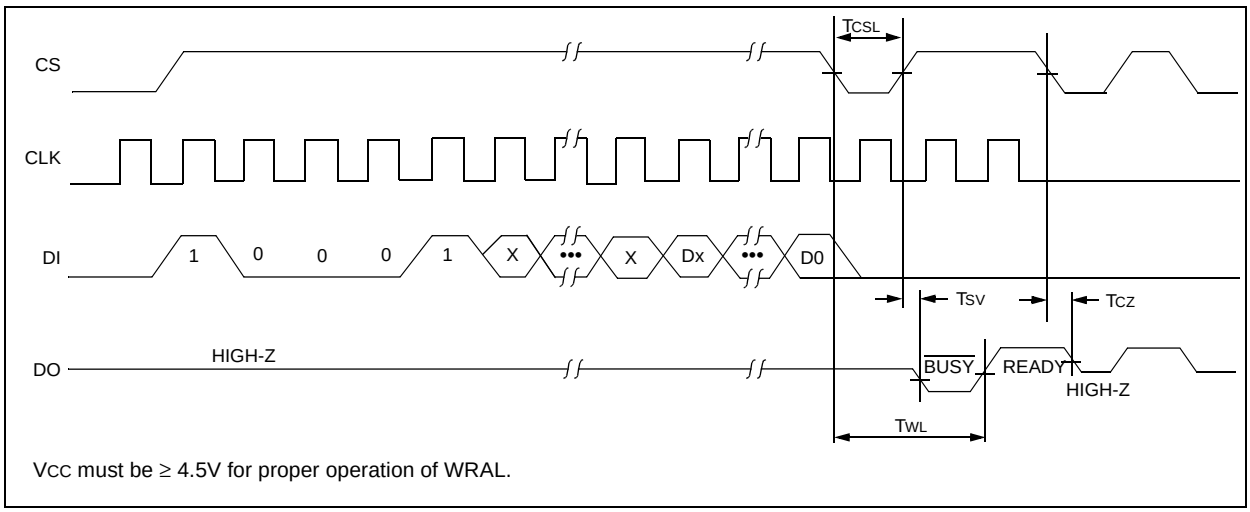
The Write All (WRAL) instruction will write the entire memory array with the data specified in the command. For 93AA66A/B/C and 93LC66A/B/C devices, after the last data bit is clocked into DI, the falling edge of CS initiates the self-timed auto-erase and programming cycle. For 93C66A/B/C devices, the self-timed auto-erase and programming cycle is initiated by the rising edge of CLK on the last data bit. Clocking of the CLK pin is not necessary after the device has entered the WRAL cycle. The WRAL command does include an automatic ERAL cycle for the device. Therefore, the WRAL instruction does not require an ERAL instruction but the chip must be in the EWEN status.

The DO pin indicates the READY/$\overline{\text{BUSY}}$ status of the device if CS is brought high after a minimum of 250 ns low (T_{CSL}).

Note: Issuing a Start bit and then taking CS low will clear the READY/$\overline{\text{BUSY}}$ status from DO.

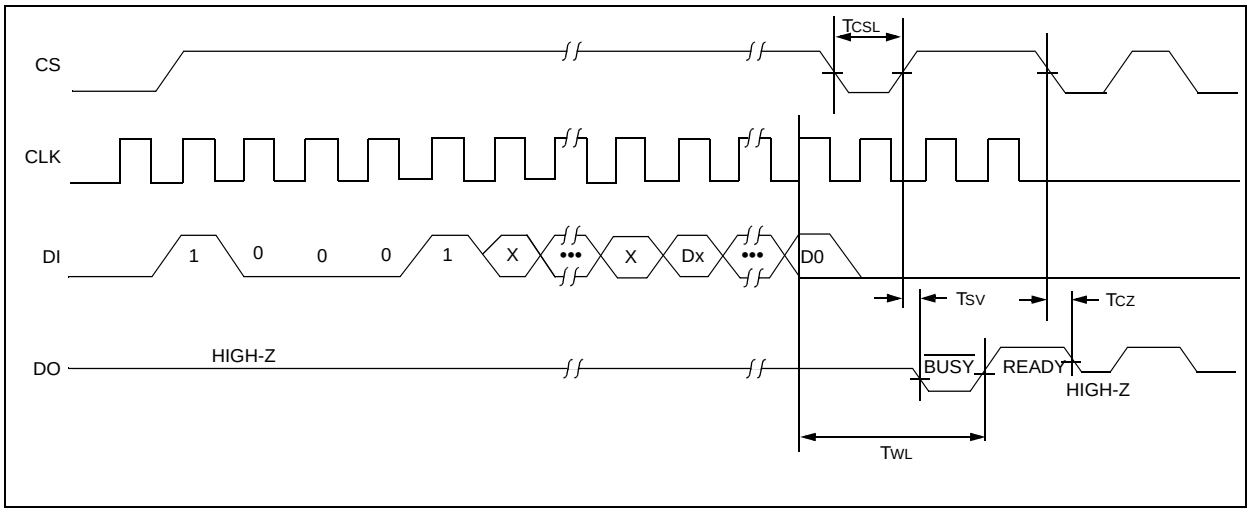
V_{CC} must be ≥ 4.5V for proper operation of WRAL.

FIGURE 2-10: WRAL TIMING FOR 93AA AND 93LC DEVICES



V_{CC} must be ≥ 4.5V for proper operation of WRAL.

FIGURE 2-11: WRAL TIMING FOR 93C DEVICES



3.0 PIN DESCRIPTIONS

TABLE 3-1: PIN DESCRIPTIONS

Name	SOIC/PDIP/ MSOP/TSSOP	SOT-23	Rotated SOIC	Function
CS	1	5	3	Chip Select
CLK	2	4	4	Serial Clock
DI	3	3	5	Data In
DO	4	1	6	Data Out
VSS	5	2	7	Ground
ORG/NC	6	N/A	8	Organization / 93XX66C No Internal Connection / 93XX66A/B
NC	7	N/A	1	No Internal Connection
VCC	8	6	2	Power Supply

3.1 Chip Select (CS)

A high level selects the device; a low level deselects the device and forces it into Standby mode. However, a programming cycle which is already in progress will be completed, regardless of the Chip Select (CS) input signal. If CS is brought low during a program cycle, the device will go into Standby mode as soon as the programming cycle is completed.

CS must be low for 250 ns minimum (TCSL) between consecutive instructions. If CS is low, the internal control logic is held in a Reset status.

3.2 Serial Clock (CLK)

The Serial Clock is used to synchronize the communication between a master device and the 93XX series device. Opcodes, address and data bits are clocked in on the positive edge of CLK. Data bits are also clocked out on the positive edge of CLK.

CLK can be stopped anywhere in the transmission sequence (at high or low level) and can be continued anytime with respect to clock high time (TCKH) and clock low time (TCKL). This gives the controlling master freedom in preparing opcode, address and data.

CLK is a “Don't Care” if CS is low (device deselected). If CS is high, but the Start condition has not been detected (DI = 0), any number of clock cycles can be received by the device without changing its status (i.e., waiting for a Start condition).

CLK cycles are not required during the self-timed Write (i.e., auto ERASE/WRITE) cycle.

After detection of a Start condition the specified number of clock cycles (respectively low-to-high transitions of CLK) must be provided. These clock cycles are required to clock in all required opcode, address and data bits before an instruction is executed. CLK and DI then become don't care inputs waiting for a new Start condition to be detected.

3.3 Data In (DI)

Data In (DI) is used to clock in a Start bit, opcode, address and data synchronously with the CLK input.

3.4 Data Out (DO)

Data Out (DO) is used in the READ mode to output data synchronously with the CLK input (TPD after the positive edge of CLK).

This pin also provides READY/$\overline{\text{BUSY}}$ status information during ERASE and WRITE cycles. READY/$\overline{\text{BUSY}}$ status information is available on the DO pin if CS is brought high after being low for minimum Chip Select low time (TCSL) and an Erase or Write operation has been initiated.

The Status signal is not available on DO, if CS is held low during the entire ERASE or WRITE cycle. In this case, DO is in the HIGH-Z mode. If status is checked after the ERASE/WRITE cycle, the data line will be high to indicate the device is ready.

Note: Issuing a Start bit and then taking CS low will clear the READY/$\overline{\text{BUSY}}$ status from DO.

3.5 Organization (ORG)

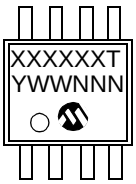
When the ORG pin is connected to VCC or Logic HI, the (x16) memory organization is selected. When the ORG pin is tied to VSS or Logic LO, the (x8) memory organization is selected. For proper operation, ORG must be tied to a valid logic level.

93XX66A devices are always x8 organization and 93XX66B devices are always x16 organization.

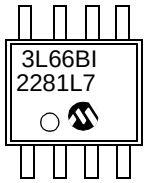
4.0 PACKAGING INFORMATION

4.1 Package Marking Information

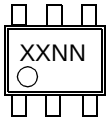
8-Lead MSOP (150 mil)



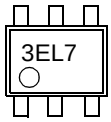
Example:



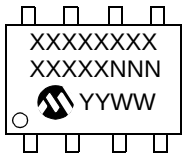
6-Lead SOT-23



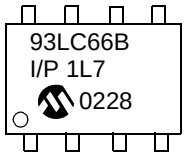
Example:



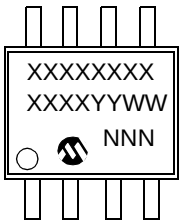
8-Lead PDIP



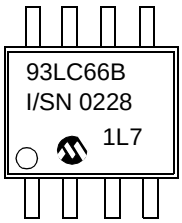
Example:



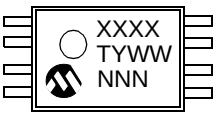
8-Lead SOIC



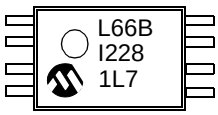
Example:



8-Lead TSSOP



Example:



MSOP 1st Line Marking Codes		
Device	std mark	Pb-free mark
93AA66A	3A66AT	GA66AT
93AA66B	3A66BT	GA66BT
93AA66C	3A66CT	GA66CT
93LC66A	3L66AT	GL66AT
93LC66B	3L66BT	GL66BT
93LC66C	3L66CT	GL66CT
93C66A	3C66AT	GC66AT
93C66B	3C66BT	GC66BT
93C66C	3C66CT	GC66CT
T = blank for commercial, “I” for Industrial, “E” for Extended.		

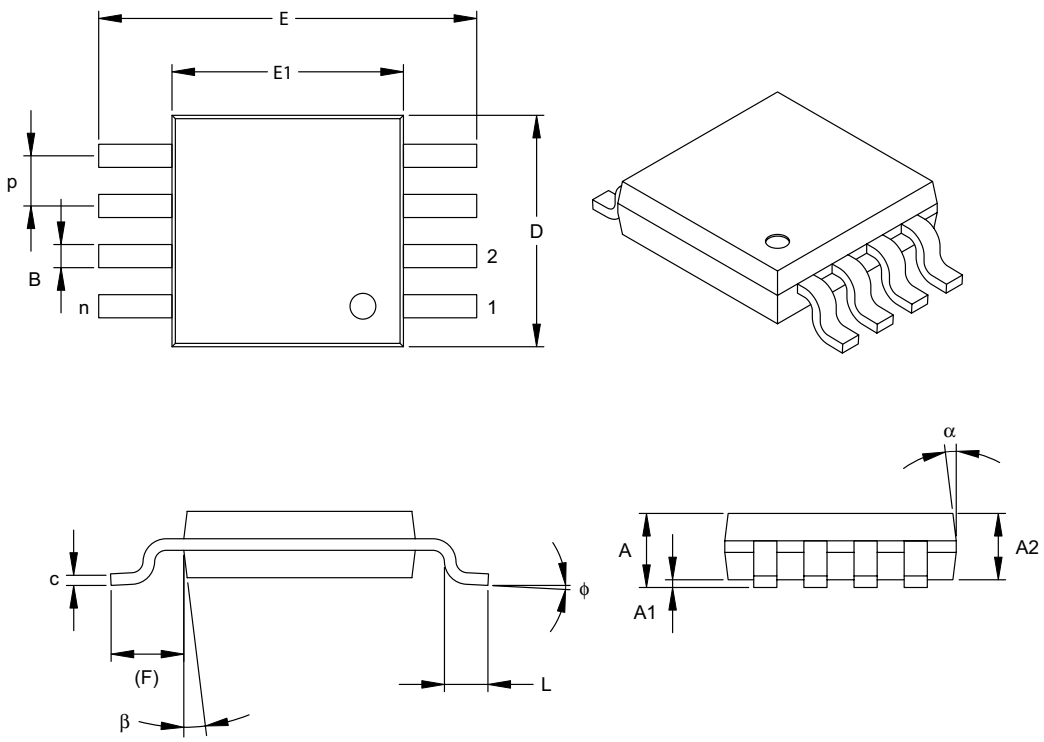
SOT23 Marking Codes		
Device	I-temp	E-temp
93AA66A	3BNN	–
93AA66B	3LNN	–
93LC66A	3ENN	3FNN
93LC66B	3PNN	3RNN
93C66A	3HNN	3JNN
93C66B	3TNN	3UNN
Pb-free topside mark is same; Pb-free noted only on carton label.		

TSSOP 1st Line Marking Codes		
Device	std mark	Pb-free mark
93AA66A	A66A	GACA
93AA66B	A66B	GACB
93AA66C	A66C	GACC
93LC66A	L66A	GLCA
93LC66B	L66B	GLCB
93LC66C	L66C	GLCC
93C66A	C66A	GCCA
93C66B	C66B	GCCB
93C66C	C66C	GCCC
Temperature grade is marked on line 2.		

Legend:	XX...X	Part number
	T	Temperature
	Blank	Commercial
	I	Industrial
	E	Extended
	YY	Year code (last 2 digits of calendar year) except TSSOP and MSOP which use only the last 1 digit
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code

Note: Custom marking available.

8-Lead Plastic Micro Small Outline Package (MS) (MSOP)



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.026 BSC			0.65 BSC	
Overall Height	A	-	-	.043	-	-	1.10
Molded Package Thickness	A2	.030	.033	.037	0.75	0.85	0.95
Standoff	A1	.000	-	.006	0.00	-	0.15
Overall Width	E		.193 TYP.			4.90 BSC	
Molded Package Width	E1		.118 BSC			3.00 BSC	
Overall Length	D		.118 BSC			3.00 BSC	
Foot Length	L	.016	.024	.031	0.40	0.60	0.80
Footprint (Reference)	F		.037 REF			0.95 REF	
Foot Angle	ϕ	0°	-	8°	0°	-	8°
Lead Thickness	c	.003	.006	.009	0.08	-	0.23
Lead Width	B	.009	.012	.016	0.22	-	0.40
Mold Draft Angle Top	α	5°	-	15°	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°	5°	-	15°

*Controlling Parameter

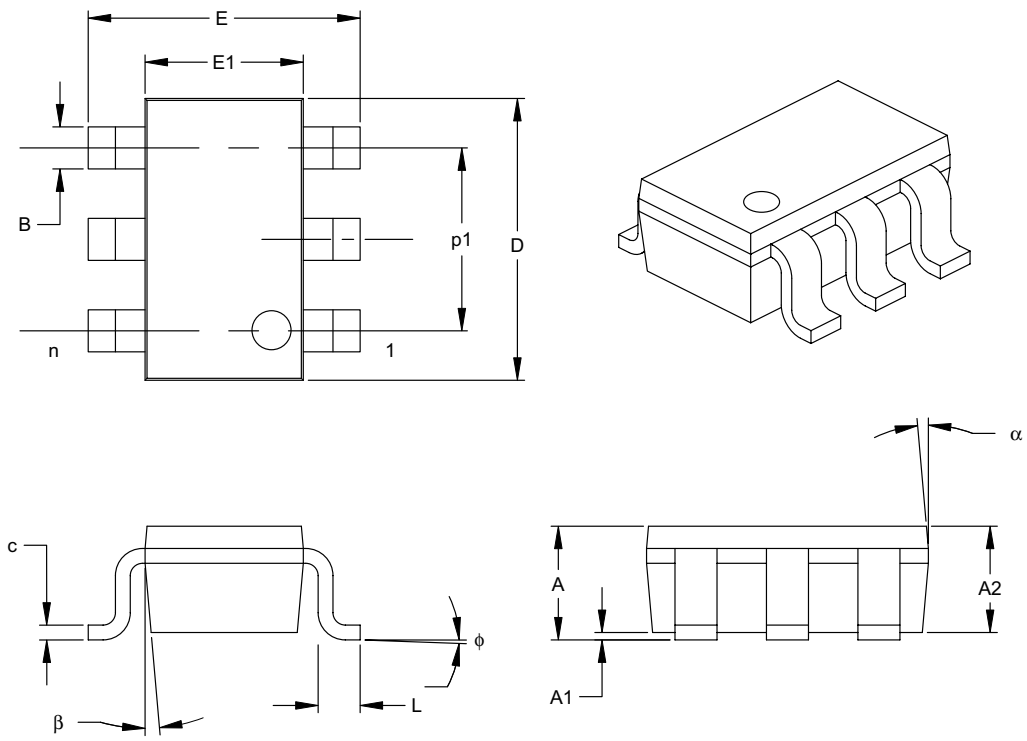
Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-187

Drawing No. C04-111

6-Lead Plastic Small Outline Transistor (OT) (SOT-23)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		6			6	
Pitch	p		.038			0.95	
Outside lead pitch (basic)	p1		.075			1.90	
Overall Height	A	.035	.046	.057	0.90	1.18	1.45
Molded Package Thickness	A2	.035	.043	.051	0.90	1.10	1.30
Standoff	A1	.000	.003	.006	0.00	0.08	0.15
Overall Width	E	.102	.110	.118	2.60	2.80	3.00
Molded Package Width	E1	.059	.064	.069	1.50	1.63	1.75
Overall Length	D	.110	.116	.122	2.80	2.95	3.10
Foot Length	L	.014	.018	.022	0.35	0.45	0.55
Foot Angle	φ	0	5	10	0	5	10
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.014	.017	.020	0.35	0.43	0.50
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

*Controlling Parameter

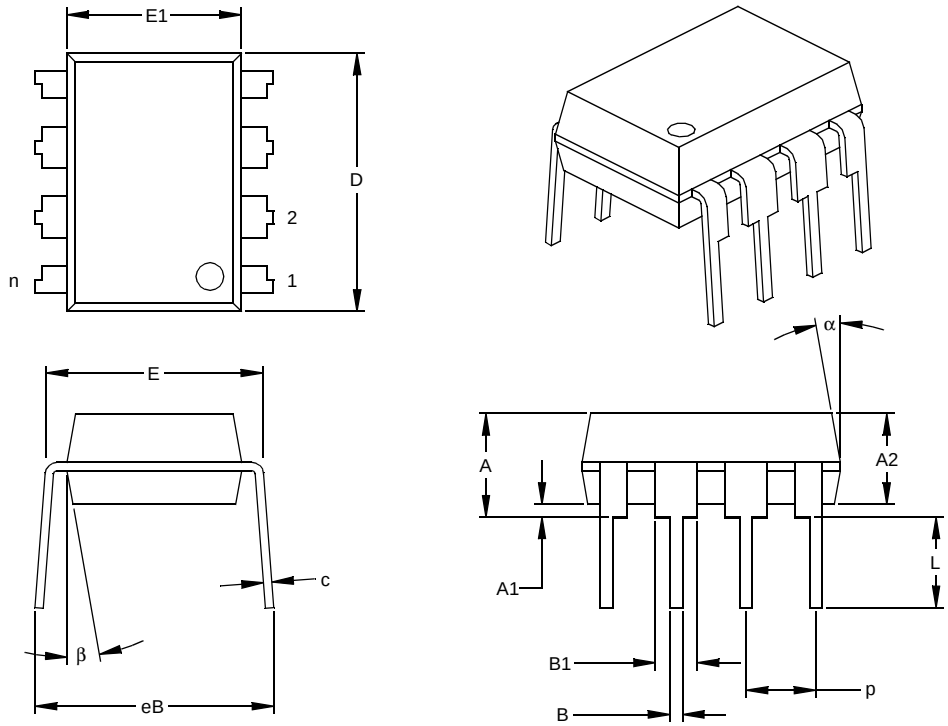
Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

JEITA (formerly EIAJ) equivalent: SC-74A

Drawing No. C04-120

8-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

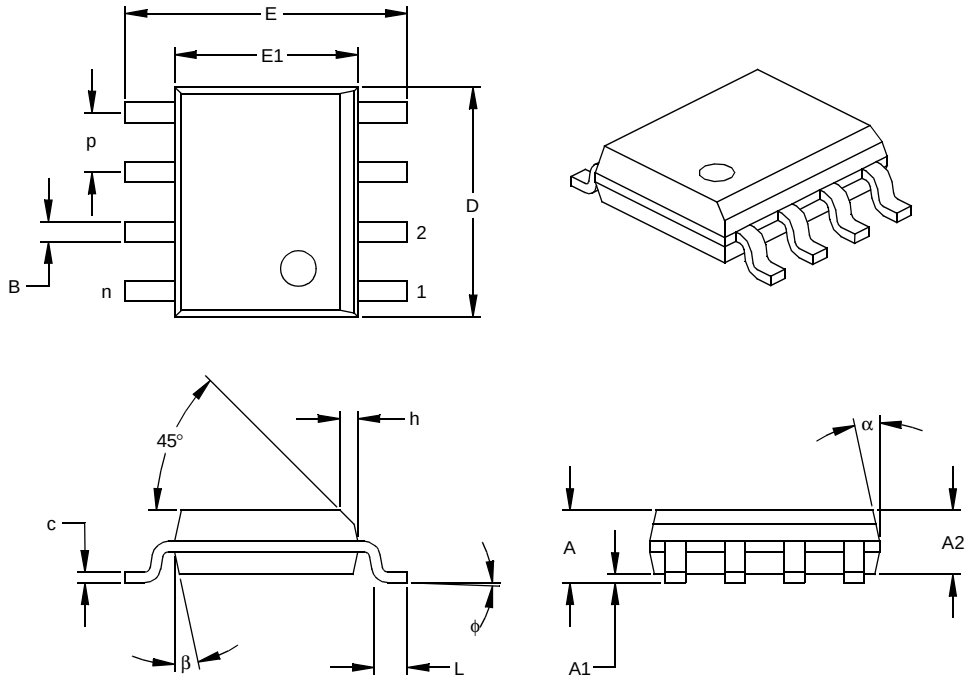


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-001
Drawing No. C04-018

8-Lead Plastic Small Outline (SN) – Narrow, 150 mil (SOIC)

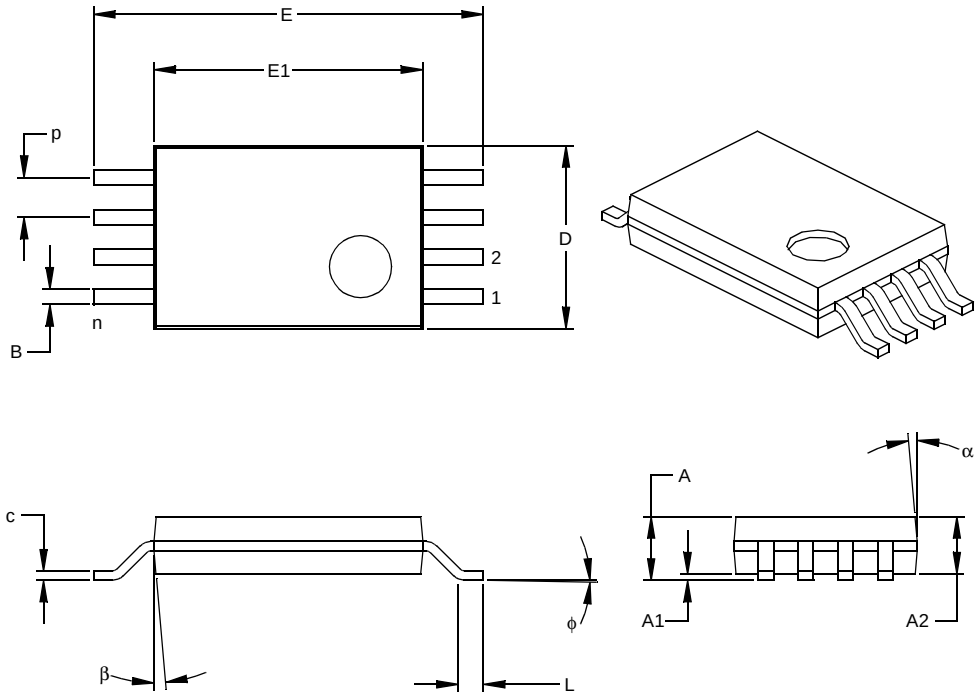


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-012
Drawing No. C04-057

8-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm (TSSOP)



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.026			0.65	
Overall Height	A			.043			1.10
Molded Package Thickness	A2	.033	.035	.037	0.85	0.90	0.95
Standoff §	A1	.002	.004	.006	0.05	0.10	0.15
Overall Width	E	.246	.251	.256	6.25	6.38	6.50
Molded Package Width	E1	.169	.173	.177	4.30	4.40	4.50
Molded Package Length	D	.114	.118	.122	2.90	3.00	3.10
Foot Length	L	.020	.024	.028	0.50	0.60	0.70
Foot Angle	ϕ	0	4	8	0	4	8
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.007	.010	.012	0.19	0.25	0.30
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005” (0.127mm) per side.
JEDEC Equivalent: MO-153
Drawing No. C04-086

APPENDIX A: REVISION HISTORY

Revision B

Corrections to Section 1.0, Electrical Characteristics.
Section 4.1, 6-Lead SOT-23 package to OT.

ON-LINE SUPPORT

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Questions:

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5. What deletions from the document could be made without affecting the overall usefulness?

6. Is there any incorrect or misleading information (what and where)?

7. How would you improve this document?

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	X	X	/XX	X
Device	Pinout	Tape & Reel	Temperature Range	Package	Lead Finish

Device	93AA66A:	4K 1.8V Microwire Serial EEPROM
	93AA66B:	4K 1.8V Microwire Serial EEPROM
	93AA66C:	4K 1.8V Microwire Serial EEPROM w/ORG
	93LC66A:	4K 2.5V Microwire Serial EEPROM
	93LC66B:	4K 2.5V Microwire Serial EEPROM
	93LC66C:	4K 2.5V Microwire Serial EEPROM w/ORG
	93C66A:	4K 5.0V Microwire Serial EEPROM
	93C66B:	4K 5.0V Microwire Serial EEPROM
	93C66C:	4K 5.0V Microwire Serial EEPROM w/ORG
Pinout:	Blank =	Standard pinout
	X =	Rotated pinout
Tape & Reel:	Blank =	Standard packaging
	T =	Tape & Reel
Temperature Range	I =	-40°C to +85°C
	E =	-40°C to +125°C
Package	MS =	Plastic MSOP (Micro Small outline, 8-lead)
	OT =	SOT-23, 6-lead (Tape & Reel only)
	P =	Plastic DIP (300 mil body), 8-lead
	SN =	Plastic SOIC (150 mil body), 8-lead
	ST =	TSSOP, 8-lead
Lead Finish:	Blank =	Standard 63% / 37% SnPb
	G =	Pure Matte Sn

Examples:

a) 93AA66C-I/MS: 4K, 512x8 or 256x16 Serial EEPROM, MSOP package, 1.8V

b) 93AA66B-I/MS: 4K, 256x16 Serial EEPROM, MSOP package, 1.8V

c) 93AA66AT-I/OT: 4K, 512x8 Serial EEPROM, SOT-23 package, tape and reel, 1.8V

d) 93AA66CT-I/MS: 4K, 512x8 or 256x16 Serial EEPROM, MSOP package, tape and reel, 1.8V

a) 93LC66A-I/MS: 4K, 512x8 Serial EEPROM, MSOP package, 2.5V

b) 93LC66BT-I/OT: 4K, 256x16 Serial EEPROM, SOT-23 package, tape and reel, 2.5V

c) 93LC66B-I/MS: 4K, 256x16 Serial EEPROM, MSOP package, 2.5V

d) 93LC66BXT-I/SNG: 4K, 256x16 Serial EEPROM, SOIC package, rotated pinout, Industrial temperature, Pb-free finish, 2.5V

a) 93C66B-I/MS: 4K, 256x16 Serial EEPROM, MSOP package, 5.0V

b) 93C66C-I/MS: 4K, 512x8 or 256x16 Serial EEPROM, MSOP package, 5.0V

c) 93C66AT-I/OT: 4K, 512x8 Serial EEPROM, SOT-23 package, tape and reel, 5.0V

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- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable.”

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Fax: 905-673-6509

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Australia
Suite 22, 41 Rawson Street
Epping 2121, NSW
Australia
Tel: 61-2-9868-6733
Fax: 61-2-9868-6755

China - Beijing
Unit 915
Bei Hai Wan Tai Bldg.
No. 6 Chaoyangmen Beidajie
Beijing, 100027, No. China
Tel: 86-10-85282100
Fax: 86-10-85282104

China - Chengdu
Rm. 2401-2402, 24th Floor,
Ming Xing Financial Tower
No. 88 TIDU Street
Chengdu 610016, China
Tel: 86-28-86766200
Fax: 86-28-86766599

China - Fuzhou
Unit 28F, World Trade Plaza
No. 71 Wusi Road
Fuzhou 350001, China
Tel: 86-591-7503506
Fax: 86-591-7503521

China - Hong Kong SAR
Unit 901-6, Tower 2, Metroplaza
223 Hing Fong Road
Kwai Fong, N.T., Hong Kong
Tel: 852-2401-1200
Fax: 852-2401-3431

China - Shanghai
Room 701, Bldg. B
Far East International Plaza
No. 317 Xian Xia Road
Shanghai, 200051
Tel: 86-21-6275-5700
Fax: 86-21-6275-5060

China - Shenzhen
Rm. 1812, 18/F, Building A, United Plaza
No. 5022 Binhe Road, Futian District
Shenzhen 518033, China
Tel: 86-755-82901380
Fax: 86-755-8295-1393

China - Shunde
Room 401, Hongjian Building
No. 2 Fengxiangnan Road, Ronggui Town
Shunde City, Guangdong 528303, China
Tel: 86-765-8395507 Fax: 86-765-8395571

China - Qingdao
Rm. B505A, Fullhope Plaza,
No. 12 Hong Kong Central Rd.
Qingdao 266071, China
Tel: 86-532-5027355 Fax: 86-532-5027205

India
Divyasree Chambers
1 Floor, Wing A (A3/A4)
No. 11, O'Shaugnessey Road
Bangalore, 560 025, India
Tel: 91-80-2290061 Fax: 91-80-2290062

Japan
Benex S-1 6F
3-18-20, Shinyokohama
Kohoku-Ku, Yokohama-shi
Kanagawa, 222-0033, Japan
Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea
168-1, Youngbo Bldg. 3 Floor
Samsung-Dong, Kangnam-Ku
Seoul, Korea 135-882
Tel: 82-2-554-7200 Fax: 82-2-558-5932 or
82-2-558-5934

Singapore
200 Middle Road
#07-02 Prime Centre
Singapore, 188980
Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan
Kaohsiung Branch
30F - 1 No. 8
Min Chuan 2nd Road
Kaohsiung 806, Taiwan
Tel: 886-7-536-4818
Fax: 886-7-536-4803

Taiwan
Taiwan Branch
11F-3, No. 207
Tung Hua North Road
Taipei, 105, Taiwan
Tel: 886-2-2717-7175 Fax: 886-2-2545-0139

EUROPE

Austria
Durisolstrasse 2
A-4600 Wels
Austria
Tel: 43-7242-2244-399
Fax: 43-7242-2244-393

Denmark
Regus Business Centre
Lautrup hoj 1-3
Ballerup DK-2750 Denmark
Tel: 45-4420-9895 Fax: 45-4420-9910

France
Parc d'Activite du Moulin de Massy
43 Rue du Saule Trapu
Batiment A - ler Etage
91300 Massy, France
Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany
Steinheilstrasse 10
D-85737 Ismaning, Germany
Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Italy
Via Quasimodo, 12
20025 Legnano (MI)
Milan, Italy
Tel: 39-0331-742611
Fax: 39-0331-466781

Netherlands
P. A. De Biesbosch 14
NL-5152 SC Drunen, Netherlands
Tel: 31-416-690399
Fax: 31-416-690340

United Kingdom
505 Eskdale Road
Winnersh Triangle
Wokingham
Berkshire, England RG41 5TU
Tel: 44-118-921-5869
Fax: 44-118-921-5820

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